



101912209

SHEET

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

KANG, Tae Woong

12-6-01



Additional name(s) of conveying party(ies) attached?
YES NO

2. Name and address of receiving party(ies)

Name: Hynix Semiconductor Inc.

Internal Address:

Street Address: San 136-1, Ami-Ri, Bubal-Eub, Ichon-Shi

City: Kyoungki-Do State: ZIP:

Country: Korea Postal Code:

Additional name(s) & address(es) attached? YES NO

3. Nature of conveyance:

- Assignment Merger
Security Agreement Change of Name
Other:

Execution Date: November 13, 2001

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s).

09/942,784

B. Patent No.(s).

Additional numbers attached? YES NO

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP

Street Address: P.O. BOX 747

City: FALLS CHURCH State: VA ZIP: 22040-0747

Country: USA

6. Total No. of applications/patents involved: one (1)

7. Total fee (37 C.F.R. § 3.41): \$40.00

- Enclosed
Authorized to be charged to deposit account, if no fee attached.

8. Deposit account number: 02-2448

(Attach triplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Joseph A. Kolasch, #22,463
Name of Person Signing/Reg. No.

Signature

December 6, 2001
Date

Total number of pages including cover sheet, attachments, and document: three (3)

12/10/2001 DBYRNE 00000030 09942784

01 FC:581

40.00 DP

JAK/JES/ndb

(Rev. 09/26/01)

UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Application No. 09/942,784

Filed August 31, 2001

Insert Name(s) of Inventor(s)

WHEREAS, Tae Woong KANG

Insert Title of Invention

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

METHOD FOR FORMING CAPACITOR OF SEMICONDUCTOR DEVICE

Insert Date of Signing of Application

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

on November 13, 2001 ; and

Insert Name of Assignee

WHEREAS, Hynix Semiconductor Inc.

Insert Address of Assignee

of San 136-1, Ami-Ri, Bubal-Eub, Ichon-Shi, Kyoungki-Do, Korea

CHECK BOX IF APPROPRIATE

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any and all foreign countries

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

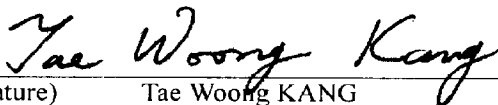
The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Nov. 13, 2001,

Name of Inventor 
(signature) Tae Woong KANG

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)